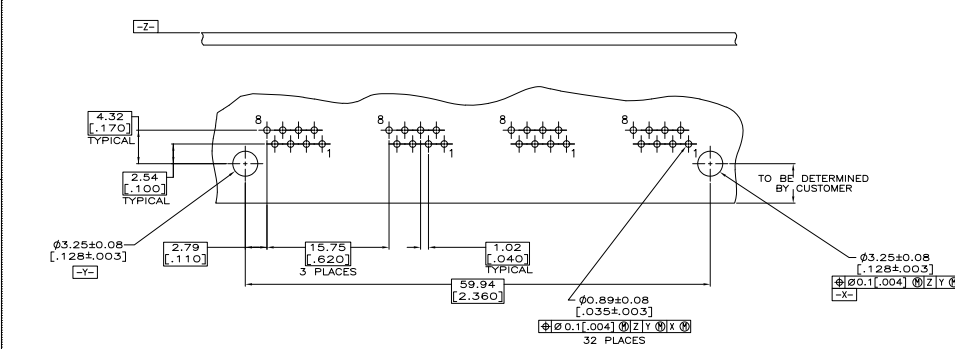
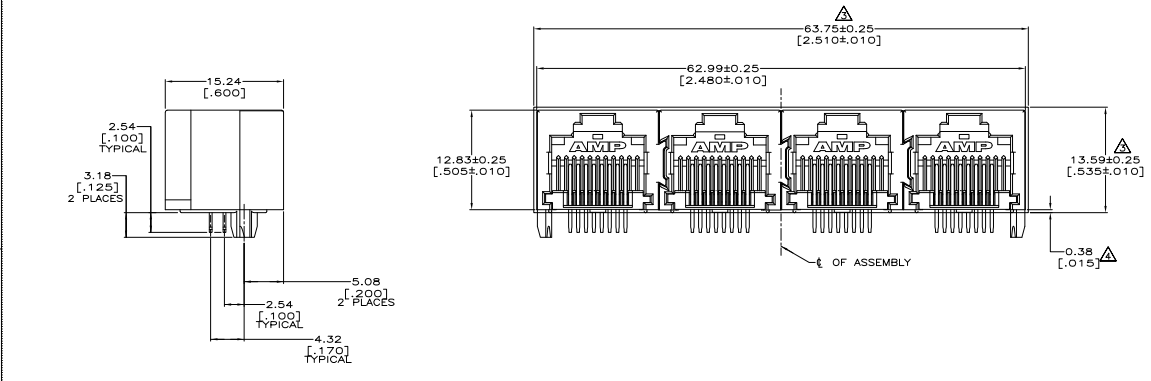


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
A		REV PER EC 0511-0201-04			10AND005 JA SF

- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC,
 BLACK; UL94V-0; IR REFLOW SOLDERING PROCESS
 COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE
 PLATED WITH 3.81µm[.000150] MINIMUM THICK
 MATTE TIN IN SOLDER AREA; 1.27µm
 [.000050] MINIMUM GOLD IN LOCALIZED PLATE
 AREA. ENTIRE TERMINAL PLATED WITH 1.27µm
 [.000050] MINIMUM THICK NICKEL.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND
 REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR
 AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT		ALCOBIA, PA 15005	TYP Electronics Corporation	
WESTMAN, PA 15389		Harrisburg, PA 17110-3608		5406528-1 PART NUMBER
INSTRUMENTS		108-1163-4	INVERTED MOD JACK ASSEMBLY, 1x4	
REV 114-2154		REV 114-2154		REVISED TO
CUSTOMER DRAWING		A1		REV A

AMP 485 REV 2/2008